

# Multi-Mode PWM Controller with Primary-Side Feedback

## Features

- Low Start-Up Current (<2uA)
- Primary-Side Feedback Control with Multi-Mode Operation
  - CCM @ Heavy Load and Low Line QR-Like Operation @ Medium Load Green mode with Valley Skip at Light Load PFM Mode at No Load
- Built-In Adjustable Load Regulation Compensation
- Constant Voltage/Constant Current Operation
- Output Short Protection
- FB Pin Open/Short Protection
- Soft Driver
- 8ms Soft-start
- OVP (Over Voltage Protection) on Vcc Pin
- On Chip OTP Protection
- SOT-26 Package with Few External Components Needed

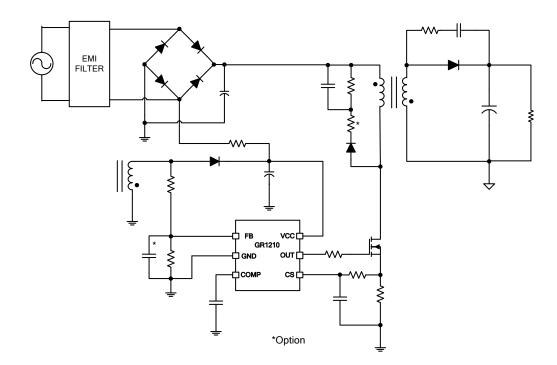
## Description

The GR1210 is a high performance primary side feedback controller with multi-mode (QR/CCM) operation for flyback converter. It minimizes the components counts and is available in a tiny SOT-26 package. Those make it an ideal design for low cost application. It provides functions of low startup current, green- mode power-saving operation, VCC over-voltage protection, and FB pin abnormal conditions sensing to prevent the circuit being damaged from the abnormal conditions.

## **Applications**

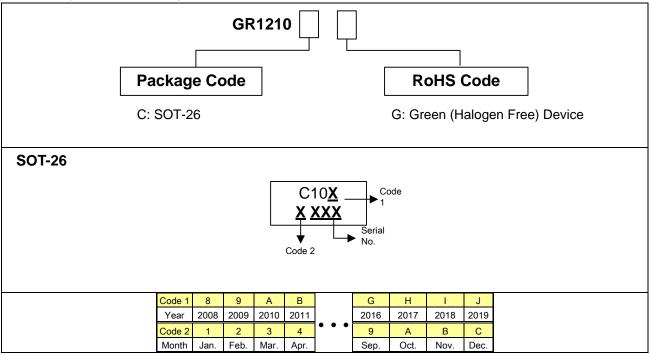
- Mobile Phone Adapter
- Lower Power AC/DC Adapter

# **Typical Application Information**





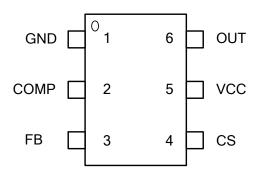
## Ordering and Marking Information



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# **Pin Configuration**

#### SOT-26 (TOP VIEW)



## **Pin Description**

Pin No.	Name	Function				
1	GND	Ground reference pin.				
2	COMP	Output of the error amplifier for voltage compensation.				
3	FB	This pin is for quasi-resonant detection and feedback control.				
4	CS	Current sense pin, connected to sense resistor for sensing the MOSFET current signal.				
5	VCC	Power supply pin.				
6	OUT	The output driver for driving the external MOSFET.				



# Absolute Maximum Ratings

Supply voltage VCC 30V
COMP, CS, FB0.3~6.0V
OUT0.3~Vcc+0.3V
Junction temperature 150°C
Storage temperature range65 $^\circ\!\mathrm{C}$ ~ 150 $^\circ\!\mathrm{C}$
SOT-26 package thermal resistance 250°C/W
Power dissipation (SOT-26, at ambient temperature = $85^{\circ}$ C) 250mW
Lead temperature (SOT-26, soldering, 10 sec) $230^{\circ}$ C
Lead temperature (All Pb free packages, soldering, 10 sec) $$ 260 $^\circ\mathrm{C}$
ESD, human body model 2.5KV
ESD, machine model 250V

**Caution:** The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed and may cause permanent damage to the IC. These are stress ratings only and functional operation of the device at these or any other condition beyond those indicated in the Electrical Characteristics section of the specification is not implied. The "Electrical Characteristics" table defines the conditions for actual device operation. Exposure to absolute maximum rated conditions for extended periods may affect device reliability

## **Recommended Operating Conditions**

Item	Min.	Max.	Unit
Operating Junction temperature	-40	125	°C
Operating ambient temperature	-40	85	°C
Start Up Resistor (AC Half side)	1M	7M	Ω
Supply voltage VCC	8.5	26.5	V
VCC Capacitor	0.68	4.7	μF
COMP pin paralleling capacitor	0.47	2.2	nF
CS pin paralleling capacitor	100	1000	pF

Note:

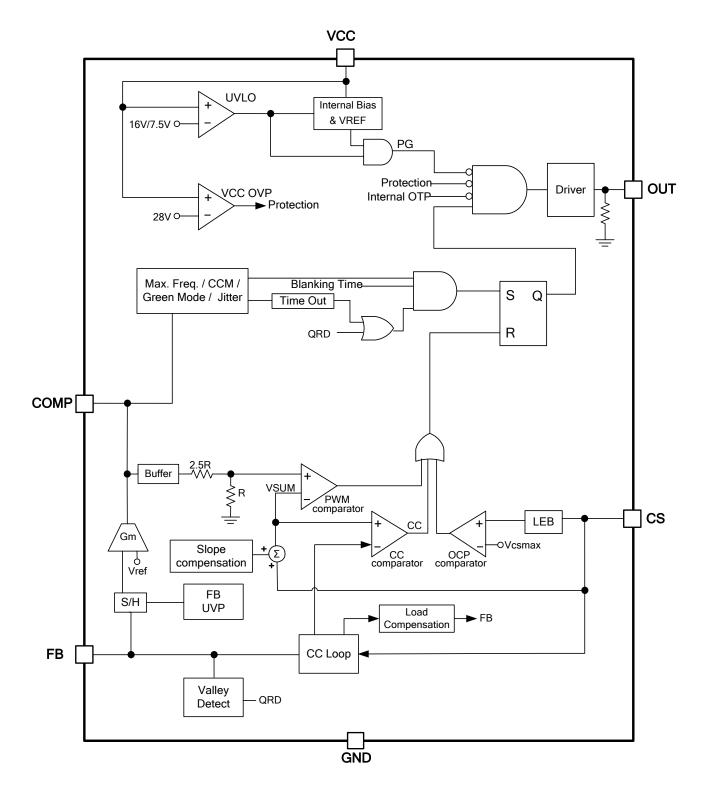
- Not to exceed the maximum junction temperature of the IC, this relates to the operating power of the IC and the thermal resistance of the IC-package as above.
- The small signal components should be placed to IC pin as possible.
- It's essential to connect VCC pin with a SMD ceramic capacitor (0.1µ F) to filter out the undesired switching noise for stable operation.
- Suggest using electrolytic capacitor or 1206 SMD ceramic capacitor as the VCC capacitor to avoid the acoustic noise from MLCC piezoelectric effect.
- Connecting a capacitor to COMP pin is also essential to filter out the undesired switching noise for stable operation.

#### **Protection Mode**

CCM Switching Frequency	FB UVP	VCC OVP		
65kHz	Auto recovery	Auto recovery		



# Block Diagram





Parameter		Min.	Тур.	Max.	Unit
SUPPLY VOLTAGE (VCC Pin)					<u> </u>
Startup current VCC=UVLO ON-0.2V	lvcc_st		1.5	2	uA
Operating current (with 1nF load on OUT pin), Vcomp = 0V	lvcc0		0.65		mA
Operating current (with 1nF load on OUT pin), Vcomp = 2.5V	lvcc25		1.5		mA
Operating current (with 1nF load on OUT pin), protection tripped			0.40		
(VCC OVP, FB UVP)	lvccpro		0.42		mA
UVLO-OFF	UVLO_off	7	7.5	8	V
UVLO-ON	UVLO_on	15	16.0	17	V
OVP level on VCC pin	VCCOVP	27	28	29	V
OVP level on VCC pin Debounce Time*			128		μs
VOLTAGE FEEDBACK (COMP Pin)					
Open loop voltage, COMP pin open	Vcomp <sub>open</sub>		4.1		V
Maximum Frequency Threshold*	V <sub>SG1</sub>		1.5		V
Green Mode Threshold*	V <sub>SG2</sub>		1.0		V
PFM Mode Threshold*	V <sub>SP1</sub>		0.8		V
Minimum Frequency Threshold*	V <sub>SP2</sub>		0.1		V
CURRENT SENSING (CS Pin)		-			
Maximum input voltage at Low Line, Vcsmax	V <sub>csmax</sub>	0.8	0.85	0.9	V
Maximum input voltage at High Line, VcsmaxL	$V_{csmax\_L}$		0.7		V
Internal Slope Compensation*			0.3		V
Mini Vcs,off, (Vcomp<0.35V)	$V_{csmin}$		0.16		V
Leading-edge blanking time	TLEB		350		ns
Input impedance*		1			MΩ
Delay to Output*			100		ns
FB (FB Pin)					
Upper Clamp Level, IZCD=0.5mA	FB_HC		4.6		V
Lower Clamp Level, IZCD=-0.3mA	FB_LC		-0.3		V
QRD Blanking Time*	T <sub>BLANK</sub>		3		μs
Mini Sample Delay Time*	$T_{sample\_min}$		1.5		μs
FB UVP Level	V <sub>FBUVP</sub>		1		V
FB UVP De-bounce Time after start-up*			8		ms

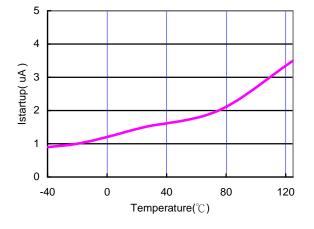


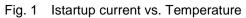
Parameter		Min.	Тур.	Max.	Unit
Error Amplifier	•	•		•	
Reference Voltage	Vref	2.47	2.5	2.53	V
Transconductance*	Gm		100		μs
OSCILLATOR					
CCM Frequency	F <sub>CCM-Mean</sub>	60	65	70	kHz
Maximum Frequency Clamp, Vcomp>V <sub>SG1</sub> *	F <sub>max</sub>		69		kHz
Green Mode Frequency	F_g		25		kHz
Minimum Frequency	F <sub>min</sub>		0.4		kHz
Jitter Frequency (CCM, Vcomp>Vs <sub>G1</sub> )*			±6		%
Soft Start Time (CS Pin)					
Soft Start Time*			8		ms
GATE DRIVER OUTPUT (OUT Pin)					
Output low level, VCC = 15V, Io = 10mA	V <sub>OL</sub>	0		1	V
Output high level, VCC = 15V, Out pin=1.5k $\Omega$ to GND	V <sub>OH1</sub>	8			V
Output High Level, VCC=UVLO-OFF+0.2V	V <sub>OH2</sub>	7		VCC	V
Rising time, load capacitance = 1000pF*	Rising		430		ns
Falling time, load capacitance = 1000pF*	Falling		75		ns
VGATE-clamp (VCC = 17V )*	V <sub>OC1</sub>		13.5		V
Maximum On Time (CCM Fs=70kHz)	T <sub>MAX_ON</sub>		10.8		μs
Internal OTP (Guaranteed by design)					
OTP*			145		°C
Hysteresis*			30		°C

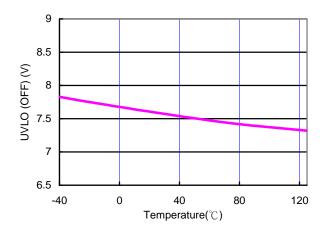
\*Guaranteed by Design.

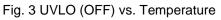


# **Typical Performance Characteristics**









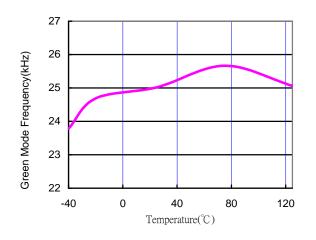


Fig. 5 Green Mode Frequency vs. Temperature

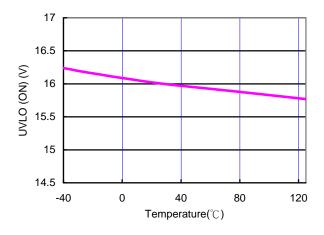


Fig. 2 UVLO (ON) vs. Temperature

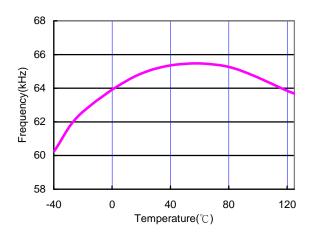


Fig. 4 CCM Frequency vs. Temperature

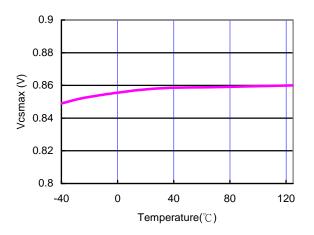
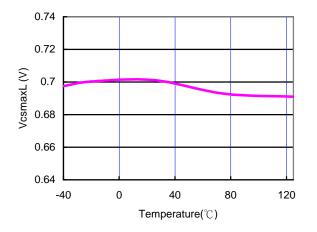


Fig. 6 Vcsmax vs. Temperature



# **Typical Performance Characteristics**



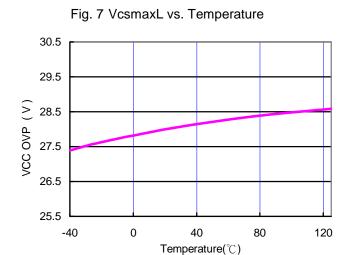


Fig. 9 VCC OVP vs. Temperature

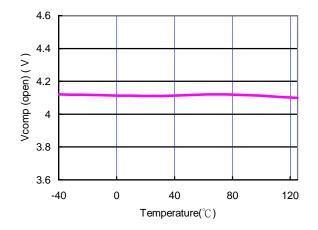


Fig. 8 Vcomp open loop voltage vs. Temperature

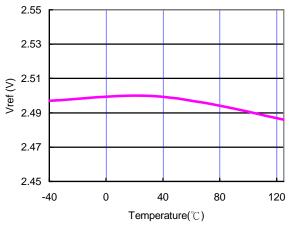


Fig. 10 Vref vs. Temperature



## **Application Information**

#### Overview

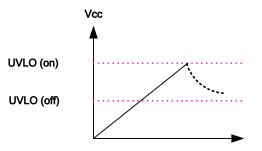
The GR1210 is a high performance multi-mode (QR/CCM) primary side feedback controller for flyback converter. This results in a low-cost solution for low power AC/DC adapters. It integrated more functions to reduce the external components counts and the size. Its major features are described as below.

#### Start-up Current

The typical start-up current is 1.5uA. Very low start-up current allows the PWM controller to increase the value of start-up resistor and then reduce the power dissipation on it.

#### Under-voltage Lockout (UVLO)

A hysteresis UVLO comparator is implemented in GR1210, then the turn-on and turn-off thresholds level are fixed at 16V and 7.5V respectively. This hysteresis shown in Fig.13 ensures that the start-up capacitor will be adequate to supply the chip during start-up.



#### Fig.13

#### Multi-Mode Operation for High Efficiency

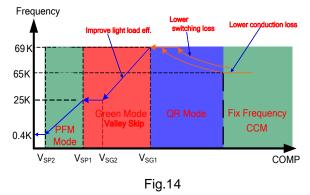
GR1210 is a multi-mode QR/CCM controller. The controller changes the mode of operation according to switching frequency and comp pin voltage, as shown in the Fig.14. At the normal operating condition, the IC operates in QR mode to reduce the switching loss. In the QR mode, the frequency varies depending on the line voltage and the load conditions. As the output load current is increased,

the on-time  $T_{ON}$  is increased, and thus the switching frequency decreases. If the switching frequency lowers than 65kHz frequency, the controller adaptively transitions to a CCM mode. Thus, small size transformer can be used with high power conversion efficiency.

As the output load current is decreased, the on-time  $T_{ON}$  is decreased, and thus the switching frequency increases. If the switching frequency increases till over the clamp of 69kHz, IC will skip the first valley to turn on in 2<sup>nd</sup> or 3<sup>rd</sup> valley.

At light load conditional, the VCOMP is lower than  $V_{SG1}$  and the system operates in green mode for high power conversion efficiency. The max switching frequency clamp will start to linearly decrease from 69kHz to 25kHz. The valley switching characteristic is still preserved in green mode. That is, when load decreases, the system automatically skip more and more valleys and the switching frequency is thus reduced.

At zero load or very light load conditions (Vcomp<  $V_{SP1}$ ), the max switching frequency clamp will linearly decrease from 25kHz to 0.4kHz, enhancing power saving.



#### **Quasi-Resonant Detection**

The QR detection block will detect auxiliary winding voltage to turn on the MOSFET.



#### Leading-edge Blanking (LEB)

Each time the power MOSFET is switched on, a turn-on spike will inevitably occur at the sense resistor. To avoid fault trigger, a leading-edge blanking time is built in. During this blanking period, the current-limit comparator is disabled and cannot switch off the gate driver.

#### Internal Slope Compensation

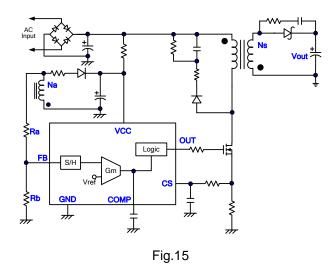
A built-in slope compensation circuit is constructed in GR1210. When the switch is on, a ramp voltage is added to the sensed voltage across the CS pin, which helps to stabilize the system and prevent sub-harmonic oscillations.

#### **Constant Voltage Operation**

GR1210 senses the auxiliary winding on the primary-side to regulate the output voltage, as shown in the Fig. 15. The auxiliary winding voltage is a reflection of the output voltage while the MOSFET is in off state. Via a resistor divider connected between the auxiliary winding and FB pin, the auxiliary voltage is sampled after the sample delay time and will be hold until the next sampling period. The internal error amplifier compares the sampled voltage with an internal reference  $V_{ref}$  (2.5V) and the error will be amplified. The error amplifier output COMP controls the duty cycle to regulate the output voltage, thus constant output voltage is given as:

$$V_{out} = 2.5 \left( 1 + \frac{Ra}{Rb} \right) \left( \frac{N_s}{N_a} \right) - V_F$$

Where  $V_F$  indicates the drop voltage of the output diode, Ra and Rb are top and bottom feedback resistor value, Ns and Na are the turns of transformer secondary and auxiliary. The leakage inductance of transformer will induce ringing to affect output regulation. To optimize the snubber circuit will minimize the high frequency ringing and achieve the best regulation.



#### Load Regulation Compensation

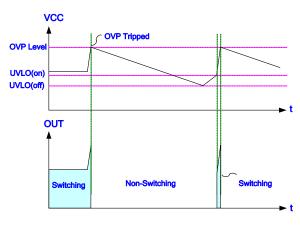
In GR1210, the load regulation compensation is implemented to achieve good voltage regulation. An offset voltage is generated at FB pin by an internal current flowing into the resister divider. The internal sink current source is proportional to the value of load current. It can also be programmed by adjusting the resistance of the voltage divider to compensate the drop for various cable lines used.

#### **Over-voltage Protection (OVP) on VCC Auto**

#### **Recovery mode**

To prevent power MOSFET from being damaged, the GR1210 is implemented an OVP function on VCC. When the VCC voltage is higher than the OVP threshold voltage, the output gate driver circuit will be shut down immediately to stop the switching of power MOSFET. The VCC OVP function is an auto-recovery type protection. If OVP happens, the pulses will be stopped and recover at the next UVLO on. The GR1210 is working in a hiccup mode as shown in Fig. 16.



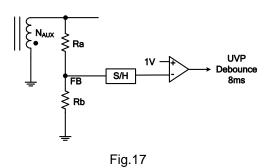




#### Output Under-voltage Protection (UVP) on FB-

#### Auto Recovery mode

To protect the circuit from damage due to output short condition, an auto-recovery type of UVP protection is implemented for it. If the FB voltage declines below 1V for over the 8ms, the protection will be activated to turn off the gate until the next UVLO-ON.



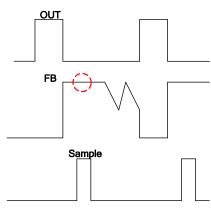


Fig.18

#### FB Pin Short Protection– Auto Recovery mode

To protect the circuit from damage due to FB short condition, an auto-recovery type of FB short protection is implemented for it. Since the FB pin voltage is clamped at 0 V when the MOSFET is turned on. The FB pin current is used for FB short protection. When FB is short over the 4 switching cycles, FB short protection is triggered.

#### Gate Clamp/Soft Driving

Driver output is clamped by an internal 13.5V clamping circuit to prevent from undesired over-voltage gate signals. And under the conditions listed below, the gate output will turn off immediately to protect the power circuit. The GR1210 also has soft driving function to minimize EMI.

#### **Fault Protection**

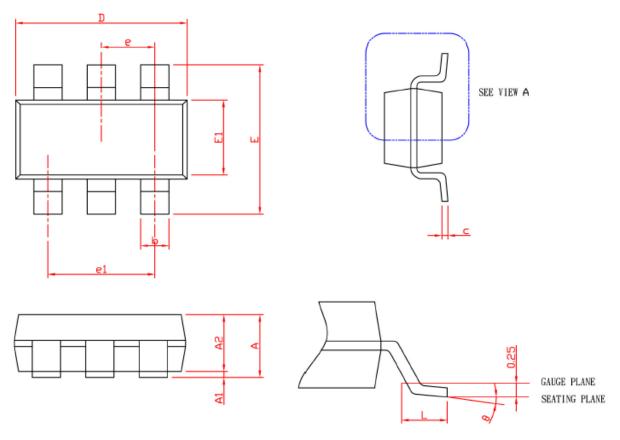
There are several critical protections integrated in the

- . CS pin floating
- . FB pin shorting (Rb shorting)
- . FB pin Open (Ra and Rb Open)
- . Ra Open



# Package Information

### SOT-26



	SOT-26					
SYMBOL	MILLIM	ETERS	INCHES			
	MIN.	MAX.	MIN.	MAX.		
А		1.45		0.057		
A1	0.00	0.15	0.000	0.006		
A2	0.90	1.30	0.035	0.051		
b	0.30	0.50	0.012	0.020		
С	0.08	0.22	0.003	0.009		
D	2.70	3.10	0.106	0.122		
E	2.60	3.00	0.102	0.118		
E1	1.40	1.80	0.055	0.071		
е	0.95 BSC		0.037 BSC			
e1	1.90 BSC		0.075	5 BSC		
L	0.30	0.60	0.012	0.024		
θ	0°	8 °	0°	8°		

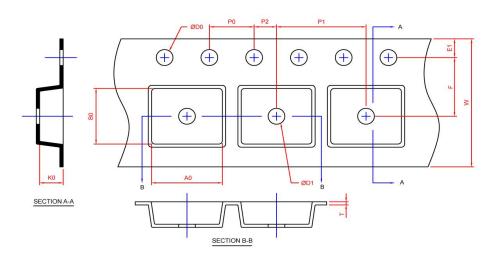
Note: 1. Followed from JEDEC MO-178 AB.

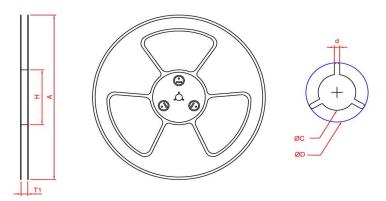
2. Dimension D and E1 do not include mold flash, protrusions or gate burrs. Mold flash, protrusions or

gate burrs shall not exceed 10 mil per side



# Carrier Tape & Reel Dimensions **sot-26**





Application	Α	н	T1	С	d	D	W	E1	F
	178.0±2.00	50 MIN.	8.4+2.00 -0.00	13.0+0.50 -0.20	1.5 MIN.	20.2 MIN.	8.0±0.30	1.75±0.10	3.5±0.05
SOT-26	P0	P1	P2	D0	D1	Т	A0	B0	K0
	4.0±0.10	4.0±0.10	2.0±0.05	1.5+0.10 -0.00	1.0 MIN.	0.6+0.00 -0.40	3.20±0.20	3.10±0.20	1.50±0.20

Application Carrier Width		Cover Tape Width	Devices Per Reel	
SOT -26	8	5.3	3000	

(mm)



Tape and Specification Reel

## **SOT 26**



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